

100-6 U. S. PTO
09/632910

	Subclass	ISSUE CLASSIFICATION
	Class	

PATENT NUMBER

U.S. UTILITY Patent Application

KW  SCANNED  Q.A.  CS ³	O.I.P.E.  PATENT DATE 
---	---

APPLICATION NO.	CONT/PRIOR	CLASS 257	SUBCLASS 616	ART UNIT 2818 3827	EXAMINER CHASSELAIS
09/632910	D F				

APPENDIX

Kohei Tatsumi
Kenji Shimokawa
Eiji Hashimoto

三

Semiconductor device provided with low melting point metal bumps and process for producing same

PTO-2040
12/89

ISSUING CLASSIFICATION

Continued on Issue Slip Inside File Jacket

TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____				ISSUE FEE	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	

WARNING:

The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.